imall

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MTM761110LBF

MOS FET MTM761110LBF

Silicon P-channel MOSFET

For Switching

Features

- Low Drain-source On-state Resistance : RDS(on) typ. = 26 m Ω (VGS = -4.5 V)
- Low Drive Voltage : 1.8 V Drive
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)
- Marking Symbol : GS

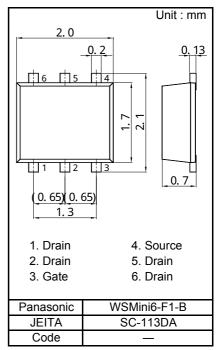
Packaging

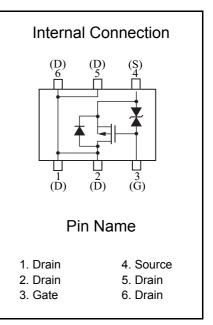
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Absolute Maximum Ratings Ta = 2	25 °C			
Parameter	Symbol	Rating	Unit	
Drain to Source Voltage	VDS	-12	V	
Gate to Source Voltage	VGS	±8	V	
Drain Current	ID	-4.0	А	
Drain Current (Pulsed)	IDp	-20	А	
Total Power Dissipation ^{*1}	PD	700	mW	
Channel Temperature	Tch	150	°C	
Operating ambient temperature	Topr	-40 to +85	°C	
Storage Temperature Range	Tstg	-55 to +150	С°	

Note : *1 Measuring on ceramic board at 40 mm \times 38 mm \times 0.2 mm.

Absolute maximum rating PD Non-heat sink shall be made 150 mW.





Panasonic

MOS FET MTM761110LBF

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	VDSS	ID = -1 mA, VGS = 0	-12			V
Drain-source cutoff current	IDSS	VDS = -10 V, VGS = 0			-0.1	μA
Gate-source cutoff current	IGSS	VGS = ±8 V, VDS = 0			±10	μA
Gate threshold voltage	Vth	ID = -1.0 mA, VDS = -6.0 V	-0.3	-0.65	-1.0	V
Drain-source ON resistance	RDS(ON)1	ID = -1.0 A, VGS = -4.5 V		26	34	mΩ
	RDS(ON)2	ID = -0.5 A, VGS = -2.5 V		30	41	
	RDS(ON)3	ID = -0.5 A, VGS = -1.8 V		36	54	
Forward transfer admittance	Yfs	ID = -1.0 A, VDS = -10 V	4.0			S
Short-circuit input capacitance (Common source)	Ciss			1400		pF
Short-circuit output capacitance (Common source)	Coss	VDS = -10 V, VGS = 0, f = 1 MHz		135		
Reverse transfer capacitance (Common source)	Crss			150		
Turn-on delay time ^{*1}	td(on)	VDD = -6 V, VGS = 0 to -4 V ID = -1.0 A		9		ns
Rise time ^{*1}	tr			11		
Turn-off delay time ^{*1}	td(off)			270		ns
Fall time ^{*1}	tf			160		

Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors. Note :

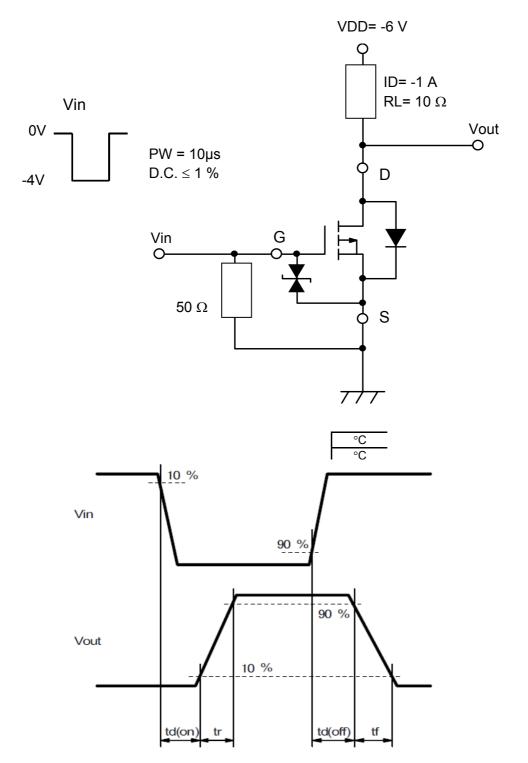
*1 Measurement circuit for Turn-on Delay Time / Turn-off Delay Time

Doc No. TT4-EA-10433 Revision. 2

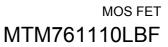


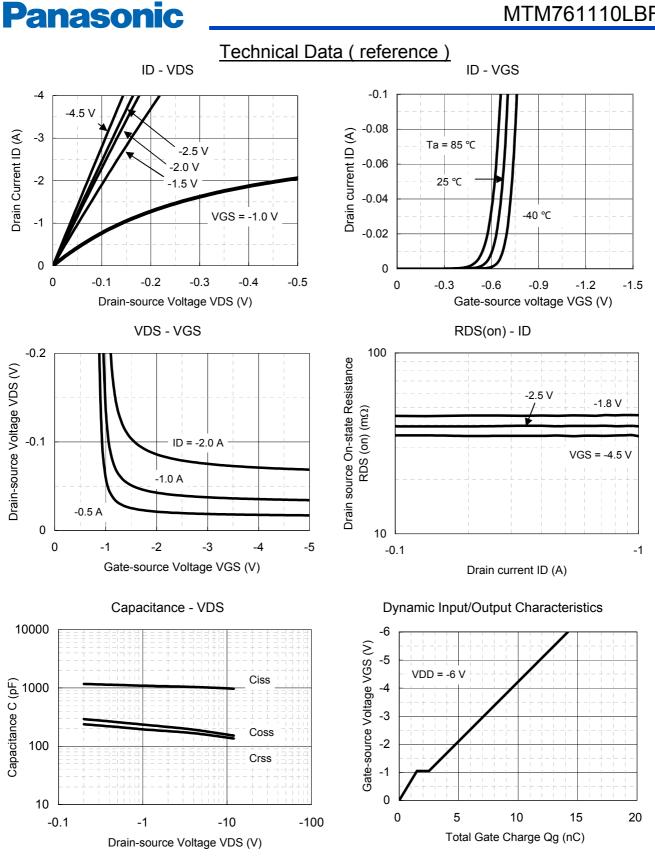
MOS FET MTM761110LBF

*1 Measurement circuit for Turn-on Delay Time / Turn-off Delay Time

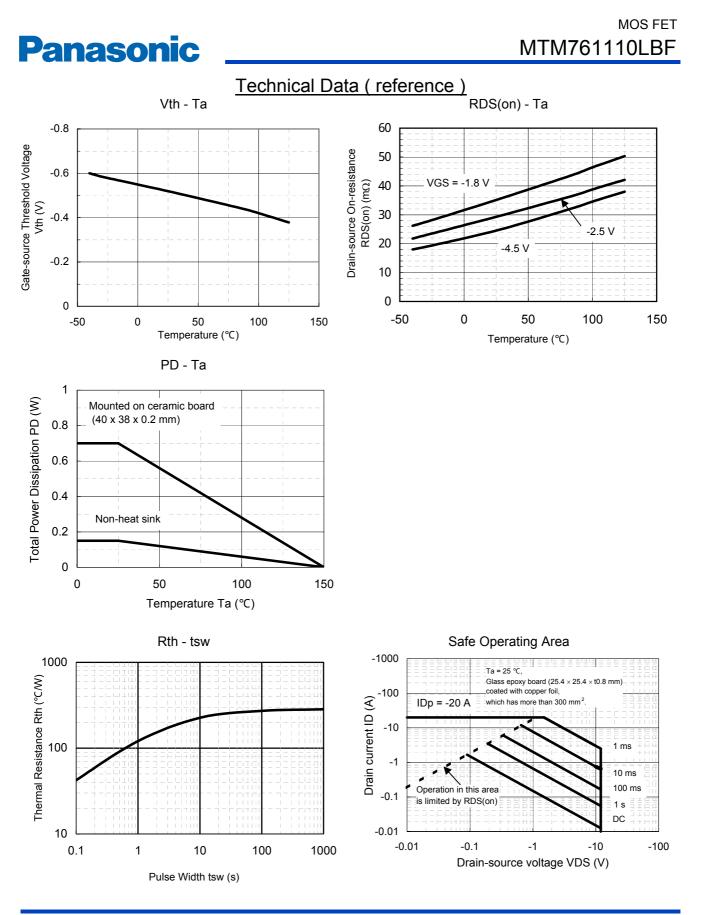


Established : 2008-02-01 Revised : 2013-10-18





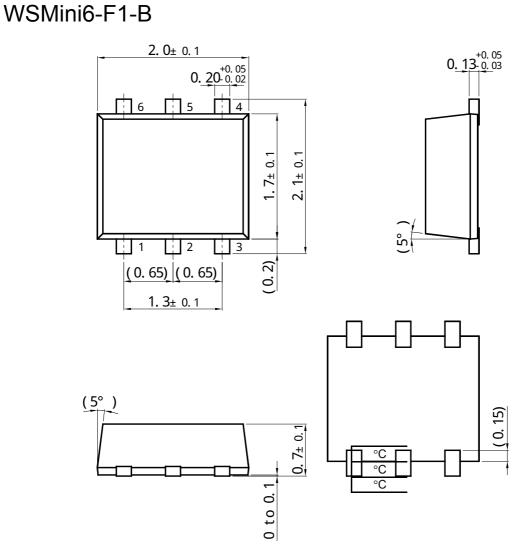
Established : 2008-02-01 Revised : 2013-10-18



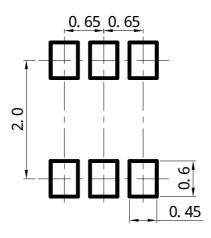


MOS FET MTM761110LBF

Unit : mm



■ Land Pattern (Reference) (Unit : mm)



Established : 2008-02-01 Revised : 2013-10-18

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